1.8-V PHASE LOCK LOOP CLOCK DRIVER

FEATURES

- **1.8-V/1.9-V Phase Lock Loop Clock Driver for Double Data Rate (DDR II) Applications**
- **Spread Spectrum Clock Compatible**
- **Operating Frequency: 125 MHz to 410 MHz**
- **Application Frequency: 160 MHz to 410 MHz**
- **Low Jitter (Cycle-Cycle): ±40 ps**
- **Low Output Skew: 35 ps**
- **Stabilization Time <6 μs**
- **Distributes One Differential Clock Input to 10 Differential Outputs**
- **High-Drive Version of CDCUA877**
- **52-Ball mBGA (MicroStar Junior™ BGA, 0,65-mm pitch)**
- **External Feedback Pins (FBIN, $\overline{\text{FBIN}}$) are Used to Synchronize the Outputs to the Input Clocks**
- **Meets or Exceeds CUA877/CUA878 Specification PLL Standard for PC2-3200/4300/5300/6400**
- **Fail-Safe Inputs**

DESCRIPTION

The CDCU2A877 is a high-performance, low-jitter, low-skew, zero-delay buffer that distributes a differential clock input pair (CK, $\overline{\text{CK}}$) to 10 differential pairs of clock outputs (Yn, $\overline{\text{Yn}}$) and to one differential pair of feedback clock outputs (FBOUT, $\overline{\text{FBOUT}}$). The clock outputs are controlled by the input clocks (CK, $\overline{\text{CK}}$), the feedback clocks (FBIN, $\overline{\text{FBIN}}$), the LVCMOS control pins (OE, OS), and the analog power input (AV_{DD}). When OE is low, the clock outputs, except FBOUT/$\overline{\text{FBOUT}}$, are disabled while the internal PLL continues to maintain its locked-in frequency. OS (output select) is a program pin that must be tied to GND or V_{DD}. When OS is high, OE functions as previously described. When OS and OE are both low, OE has no affect on Y7/$\overline{\text{Y7}}$, they are free running. When AV_{DD} is grounded, the PLL is turned off and bypassed for test purposes.

When both clock inputs (CK, $\overline{\text{CK}}$) are logic low, the device enters in a low power mode. An input logic detection circuit on the differential inputs, independent from input buffers, detects the logic low level and performs in a low power state where all outputs, the feedback, and the PLL are off. When the clock inputs transition from being logic low to being differential signals, the PLL turns back on, the inputs and the outputs are enabled, and the PLL obtains phase lock between the feedback clock pair (FBIN, $\overline{\text{FBIN}}$) and the clock input pair (CK, $\overline{\text{CK}}$) within the specified stabilization time.

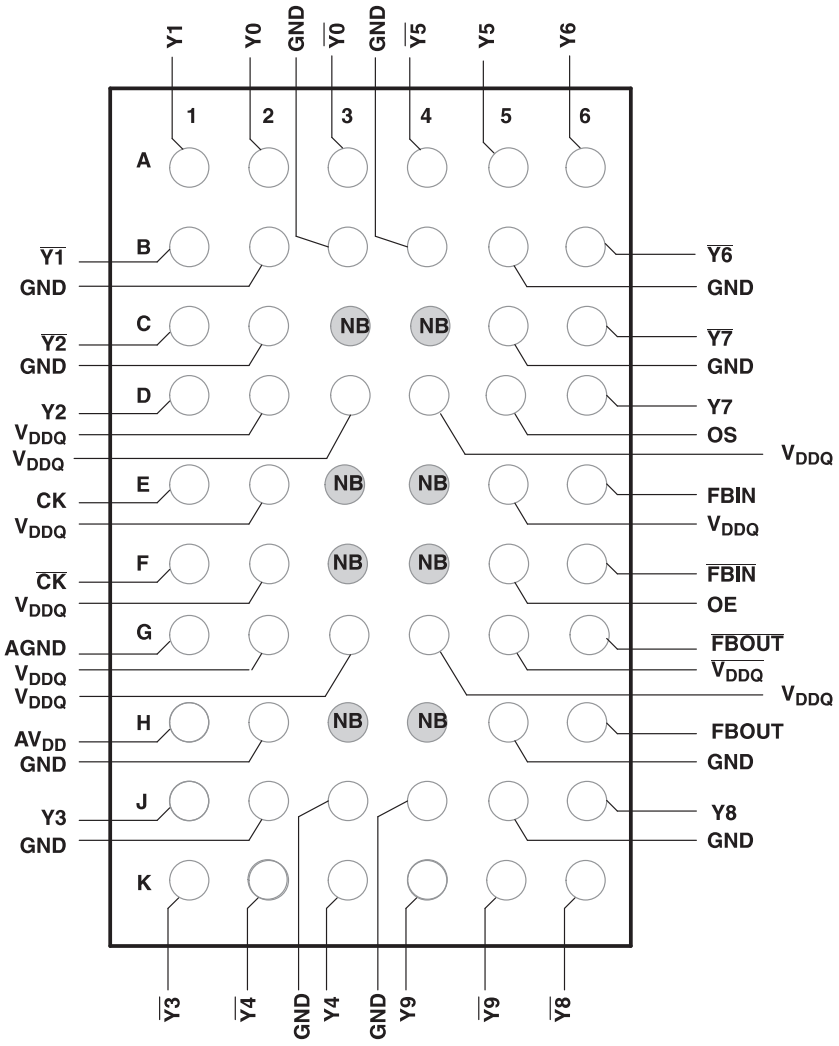
The CDCU2A877 is able to track spread spectrum clocking (SSC) for reduced EMI. This device operates from 0°C to 70°C.

AVAILABLE OPTIONS

T_A	52-Ball BGA (1)
0°C to 70°C	CDCU2A877ZQL

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

MicroStar™ Junior (GQL) Package
(TOP VIEW)



NC – No Connection
NB – No Ball

Table 1. Terminal Functions

NAME	BGA	MLF	I/O	DESCRIPTION
AGND	G1	7		Analog ground
AV_{DD}	H1	8		Analog power
CK	E1	4	I	Clock input with a (10 kΩ to 100 kΩ) pulldown resistor
$\overline{CK}$	F1	5	I	Complementary clock input with a (10 kΩ to 100 kΩ) pulldown resistor
FBIN	E6	27	I	Feedback clock input
$\overline{FBIN}$	F6	26	I	Complementary feedback clock input
FBOUT	H6	24	O	Feedback clock output
$\overline{FBOUT}$	G6	25	O	Complementary feedback clock output
OE	F5	22	I	Output enable (asynchronous)
OS	D5	21	I	Output select (tied to GND or VDD)
GND	B2, B3, B4, B5, C2, C5, H2, H5, J2, J3, J4, J5	10		Ground
V_{DDQ}	D2, D3, D4, E2, E5, F2, G2, G3, G4, G5	1, 6, 9, 15, 20, 23, 28, 31, 36		Logic and output power
Y[0:9]	A2, A1, D1, J1, K3, A5, A6, D6, J6, K4	38, 39, 3, 11, 14, 34, 33, 29, 19, 16	O	Clock outputs
$\overline{Y[0:9]}$	A3, B1, C1, K1, K2, A4, B6, C6, K6, K5	37, 40, 2, 12, 13, 35, 32, 30, 18, 17	O	Complementary clock outputs

Table 2. Function Table

INPUTS					OUTPUTS				PLL
AV_{DD}	OE	OS	CK	$\overline{CK}$	Y	$\overline{Y}$	FBOUT	$\overline{FBOUT}$	
GND	H	X	L	H	L		L	H	Bypassed/Off
GND	H	X	H	L	H		H	L	Bypassed/Off
GND	L	H	L	H	L_Z	L_Z	L	H	Bypassed/Off
GND	L	L	H	L	LZ Y7 Active	LZ $\overline{Y7}$ Active	H	L	Bypassed/Off
1.8 V Nomnal	L	H	L	H	L_Z	L_Z	L	H	On
1.8 V Nomnal	L	L	H	L	LZ Y7 Active	LZ $\overline{Y7}$ Active	H	L	On
1.8 V Nomnal	H	X	L	H	L	H	L	H	On
1.8 V Nomnal	H	X	H	L	H	L	H	L	On
1.8 V Nomnal	X	X	LH	L	L_Z	L_Z	L_Z	L_Z	Off
X	X	X	H	H	Reserved				

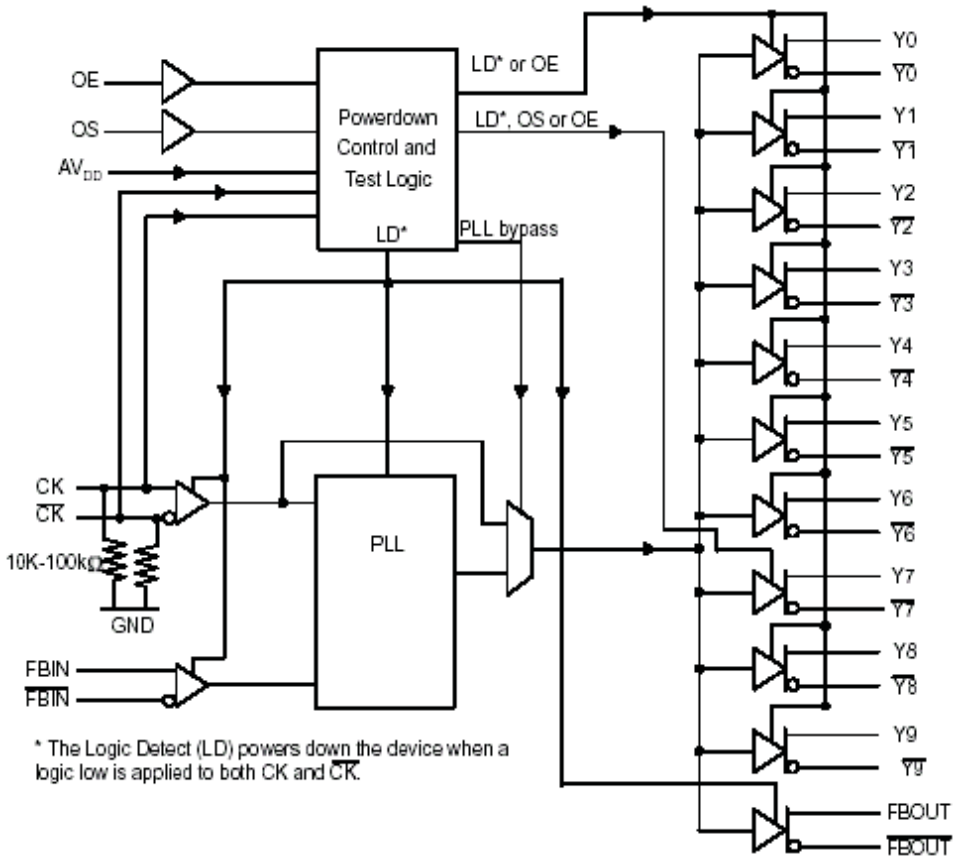


Figure 1. Logic Diagram (Positive Logic)

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)(1)

			VALUE	UNIT
V_{DDQ} A_{VDD}	Supply voltage range		–0.5 tp 2.5	V
V_I	Input voltage range(2)(3)		–0.5 to V_{DDQ} + 0.5	V
V_O	Output voltage range(2)(3)		–0.5 to V_{DDQ} + 0.5	V
I_{IK}	Input clamp current, (V_I < 0 or V_I > V_{DDQ})		±50	mA
I_{OK}	Output clamp voltage, (V_O < 0 or V_O > V_{DDQ})		±50	mA
I_O	Continuous output current, (V_O = 0 to V_{DDQ})		±50	mA
I_{DDC}	Continuous current through each V_{DDQ} or GND		±100	mA
$R_{\theta JA}$	Thermal resistance, junction-to-ambient(4)	No airflow	151.9	K/W
		Airllflow 150 ft/min	146.1	
$R_{\theta JC}$	Thermal resistance, junction-to-case(4)	No airflow	102.4	
T_{stg}	Storage temperature range		–65 to 150	°C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
(3) This value is limited to 2.5 V maximum.
(4) The package thermal impedance is calculated in accordance with JESD51 and JEDEC2S1P (high-k board).

RECOMMENDED OPERATING CONDITIONS

			MIN	NOM	MAX	UNIT
V_{DDQ}	Output supply voltage		1.7	1.8	1.9	V
AV_{DD}	Supply voltage(1)			V_{DDQ}		
V_{IL}	Low-level input voltage(2)	OE, OS			$0.35 \times V_{DDQ}$	V
V_{IH}	High-level input voltage(2)	CK, $\overline{CK}$	$0.65 \times V_{DDQ}$			V
I_{OH}	High-level output current (see Figure 2)				–18	mA
I_{OL}	Low-level output current (see Figure 2)				18	mA
V_{IX}	Input differential-pair cross voltage		$(V_{DDQ}/2)$-0.15		$(V_{DDQ}/2)$+0.15	V
V_I	Input voltage level		–0.3		V_{DDQ}+0.3	V
V_{ID}	Input differential voltage(2) (see Figure 4)	DC	0.3		V_{DDQ}+0.4	V
		AC	0.6		V_{DDQ}+0.4	V
T_A	Operating free-air temperature		0		70	°C

(1) The PLL is turned off and bypassed for test purposes when AV_{DD} is grounded. During this test mode, V_{DDQ} remains within the recommended operating conditions and no timing parameters are ensured.

(2) V_{ID} is the magnitude of the difference between the input level on CK and the input level on $\overline{CK}$, see Figure 4 for definition. The CK and $\overline{CK}$ V_{IH} and V_{IL} limits define the dc low and high levels for the logic detect state.

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range

PARAMETER	Low-level output voltage		TEST CONDITIONS	AV_{DD}, V_{DDG}	MIN	TYP	MAX	UNIT
V_{IK}	Input (cl inputs)		I_I = –18 mA	1.7 V			–1.2	V
V_{OH}	High-level output voltage		I_{OH} = -100 A	1.7 V to 1.9 V	VDDQ – 0.2			V
			I_{OH} = –18 mA	1.7 V	1.1			
V_{OL}	Low-level output voltage		I_{OL} = 100 µA				0.1	V
			I_{OL} = 18 mA	1.7 V			0.6	
$I_{O(DL)}$	Low-level output current, disabled		$V_{O(DL)}$ = 100 mV, OE = L	1.7 V	100			µA
V_{OD}	Differential output voltage(1)			1.7 V	0.6			V
I_I	Input current	CK, $\overline{CK}$		1.9 V			±250	µA
		OE, OS, FBIN, $\overline{FBIN}$		1.9 V			±10	
$I_{DD(LD)}$	Supply current, static (I_{DDQ} + I_{ADD})		CK and $\overline{CK}$ = L	1.9 V			500	µA
I_{DD}	Supply current, dynamic (I_{DDQ} + I_{ADD}) (see (2) for C_{PD} calculation)		CK and $\overline{CK}$ = 410 MHz, All outputs are open (not connected to a PCB)	1.9 V			300	mA
			All outputs are loaded with 2 pF and 120-Ω termination resistor, CK and $\overline{CK}$ = 410 MHz	1.9 V			325	mA
C_I	Input capacitance	CK, $\overline{CK}$	V_I = V_{DD} or GND	1.8 V	2		3	pF
		FBIN, $\overline{FBIN}$	V_I = V_{DD} or GND	1.8 V	2		3	
$C_{I(\Delta)}$	Change in input current	CK, $\overline{CK}$	V_I = V_{DD} or GND	1.8 V			0.25	pF
		FBIN, $\overline{FBIN}$	V_I = V_{DD} or GND	1.8 V			0.25	

(1) V_{OD} is the magnitude of the difference between the true and complimentary outputs. See Figure 4 for a definition.
(2) Total I_{DD} = I_{DDQ} + I_{ADD} = f_{CK}× C_{PD}× V_{DDQ}, solving for C_{PD} = (I_{DDQ} + I_{ADD})/(f_{CK} × V_{DDQ}) where f_{CK} is the input frequency, V_{DDQ} is the power supply, and C_{PD} is the power dissipation capacitance.

TIMING REQUIREMENTS

over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{CK}	Clock frequency (operating)(1)(2)	AV_{DD}, V_{DD} = 1.8 V ±0.1 V	125		410	MHz
f_{CK}	Clock frequency (application)(1)(3)	AV_{DD}, V_{DD} = 1.8 V ±0.1 V	160		410	MHz
t_{DC}	Duty cycle, input clock	AV_{DD}, V_{DD} = 1.8 V ±0.1 V	40%		60%	
t_L	Stabilization time(4)	AV_{DD}, V_{DD} = 1.8 V ±0.1 V			6	µs

(1) The PLL must be able to handle spread spectrum induced skew.
(2) Operating clock frequency indicates a range over which the PLL must be able to lock, but in which it is not required to meet the other timing parameters (used for low speed system debug).
(3) Application clock frequency indicates a range over which the PLL must meet all timing parameters.
(4) Stabilization time is the time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal, within the value specified by the static phase offset $t_{(\phi)}$, after power up. During normal operation, the stabilization time is also the time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal when CK and $\overline{CK}$ go to a logic low state, enter the power-down mode, and later return to active operation. CK and $\overline{CK}$ may be left floating after they have been driven low for one complete clock cycle.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{en}	Enable time, OE to any Y/$\overline{Y}$	See Figure 12			8	ns
t_{dis}	Disable time, OE to any Y/$\overline{Y}$	See Figure 12			8	ns
$t_{jit(cc+)}$	Cycle-to-cycle period jitter(2)	160 MHz to 410 MHz, See Figure 5	0		40	ps
$t_{jit(cc-)}$			0		–40	
$t_{(\phi)}$	Static phase offset time(3)	SeeFigure 4	–50		50	ps
$t_{(\phi)dyn}$	Dynamic phase offset time,(4)	See Figure 11	–20		20	ps
$t_{sk(o)}$	Output clock skew(4)	See Figure 7			35	ps
$t_{jit(per)}$	Period jitter(5)(2)	160 MHz to 270 MHz, See Figure 8	–30		30	ps
		271 MHz to 410 MHz, See Figure 8	–20		20	
$t_{jit(hper)}$	Half-period jitter(5)(2)	160 MHz to 270 MHz, See Figure 9	–75		75	ps
		271 MHz to 410 MHz, See Figure 9	–50		50	
$\Sigma t_{(su)}$	$\lvert t_{jit(per)}\rvert + \lvert t_{(\phi)dyn}\rvert + t_{sk(o)}$(6)	271 MHz to 410 MHz			80	ps
$\Sigma t_{(h)}$	$\lvert t_{(\phi)dyn}\rvert + + t_{sk(o)}$(6)	271 MHz to 410 MHz			60	ps
SR	Slew rate, OE	See Figure 3 and Figure 8	0.5			V/ns
	Input clock skew rate	See Figure 3 and Figure 8	1	2.5	4	
	Output clock slew rate(7)(8)	See Figure 3 and Figure 8	1.5	2.5	3	
V_{OX}	Output differential-pair cross voltage(9)	See Figure 2	$(V_{DDQ}/2) – 0.1$		$(V_{DDQ}/2) + 0.1$	V
	SSC modulation frequency		30		33	kHz
	SSC clock input frequency deviation		0%		–0.5%	
	PLL loop bandwidth		2			MHz

(1) There are two different terminations that are used with the following tests. The load/board in Figure 2 is used to measure the input and output differential-pair cross voltage only. The load/board in Figure 3 is used to measure all other tests. For consistency, equal length cables must be used.
(2) This parameter is assured by design and characterization.
(3) Phase static offset time does not include jitter.
(4) For full frequency range of 160MHz to 410MHz.
(5) Period jitter, half-period jitter specifications are separate specifications that must be met independently of each other.
(6) In the frequency range of 271 MHz to 410 MHz, the minimum and maximum values of $t_{jit(per)}$ and $t_{(\phi)dyn}$ and the maximum value for $t_{sk(o)}$ must not exceed the corresponding minimum and maximum values of the 160 MHz to 270 MHz range. In addition, the sum of the specified values for $|t_{jit(per)}|$, $|t_{(\phi)dyn}|$, and $t_{sk(o)}$ must meet the requirements for the $\Sigma t_{(su)}$ and the sum of the specified values for $|t_{(\phi)dyn}|$ and $t_{sk(o)}$ must meet the requirements for the $\Sigma t_{(h)}$.
(7) The output slew rate is determined from the IBIS model into the load shown in Figure 4.
(8) To eliminate the impact of input slew rates on static phase offset, the input skew rates of reference clock input CK and $\overline{CK}$ and feedback clock inputs FBIN and $\overline{FBIN}$ are recommended to be nearly equal. The 2.5-V/ns skew rates are shown as a recommended target. Compliance with these typical values is not mandatory if it can adequately shown that alternative characteristics meet the requirements of the registered DDR2 DIMM application.
(9) Output differential-pair cross voltage specified at the DRAM clock input or the test load.

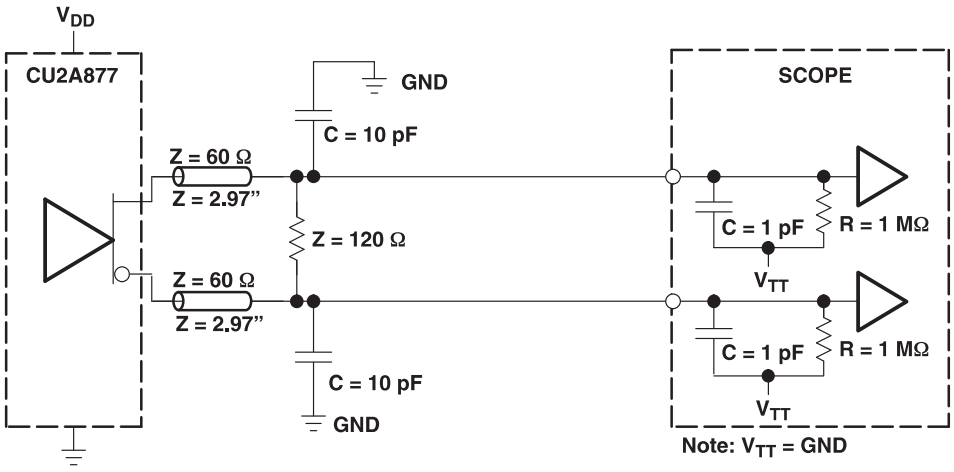


Figure 2. Output Load Test Circuit 1 (Using High-Impedance Probe)

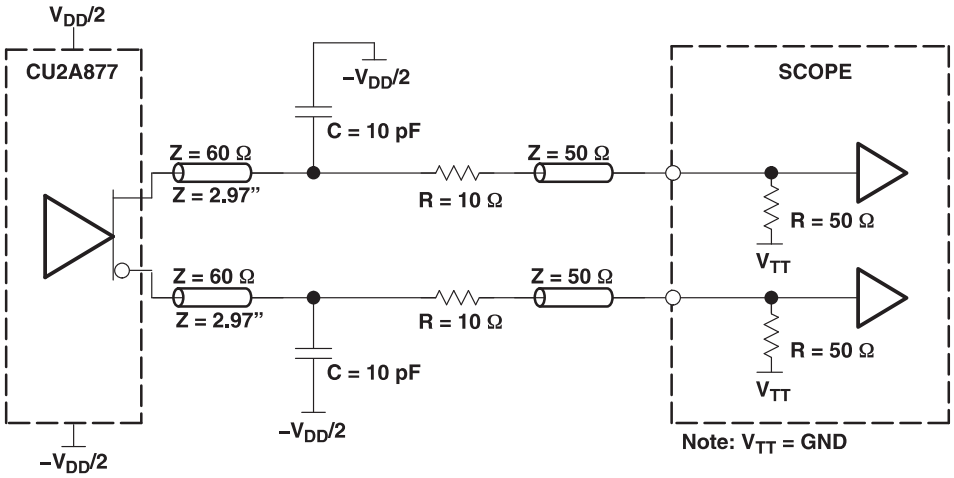


Figure 3. Output Load Test Circuit 2 (Using SMA Coaxial Cable)

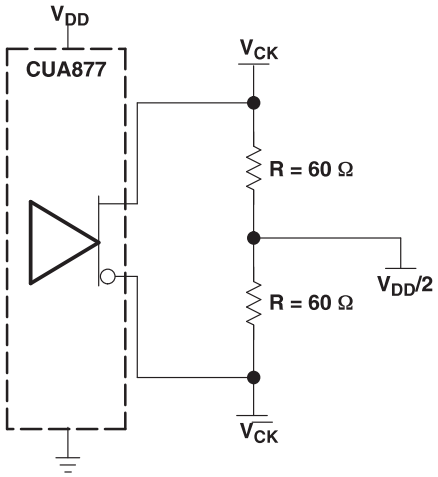


Figure 4. IBIS Model Output Load

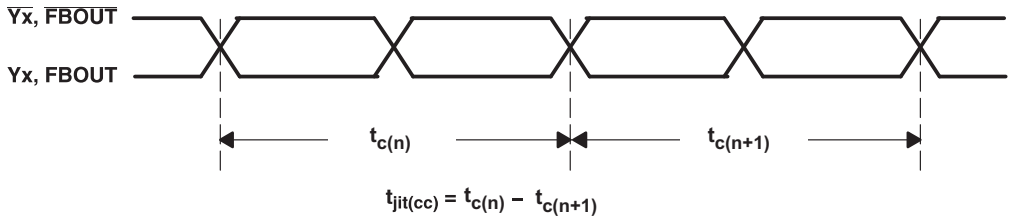


Figure 5. Cycle-To-Cycle Period Jitter

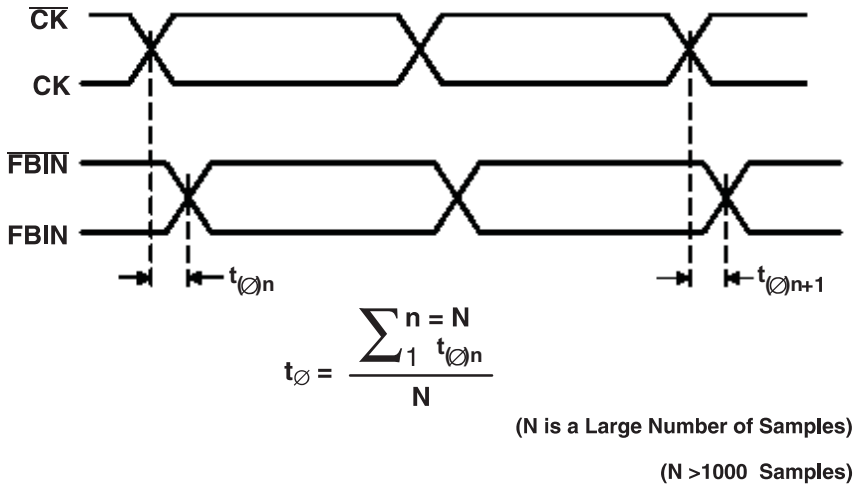


Figure 6. Static Phase Offset

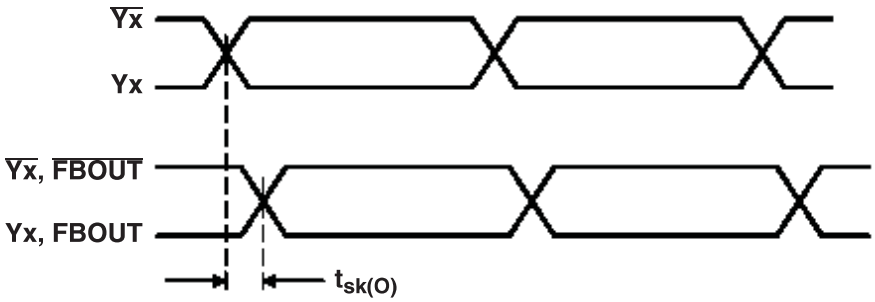


Figure 7. Output Skew

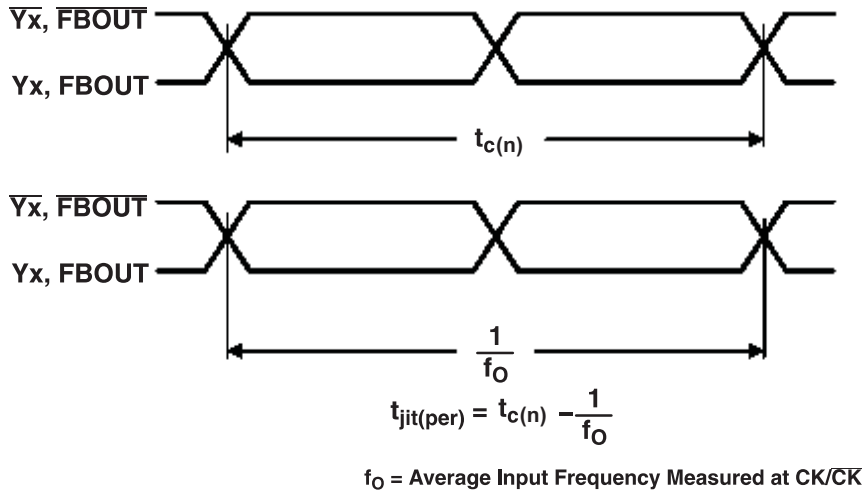


Figure 8. Period Jitter

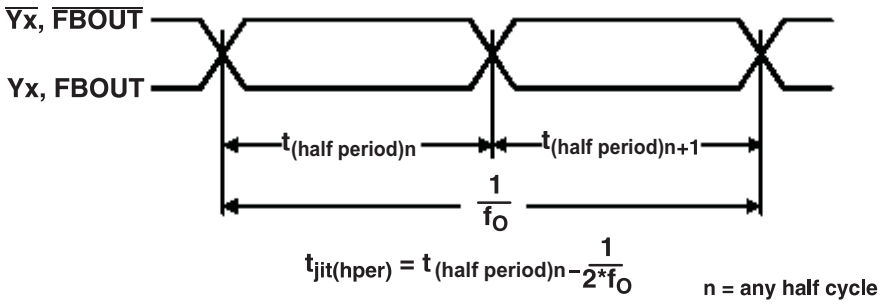


Figure 9. Half-Period Jitter

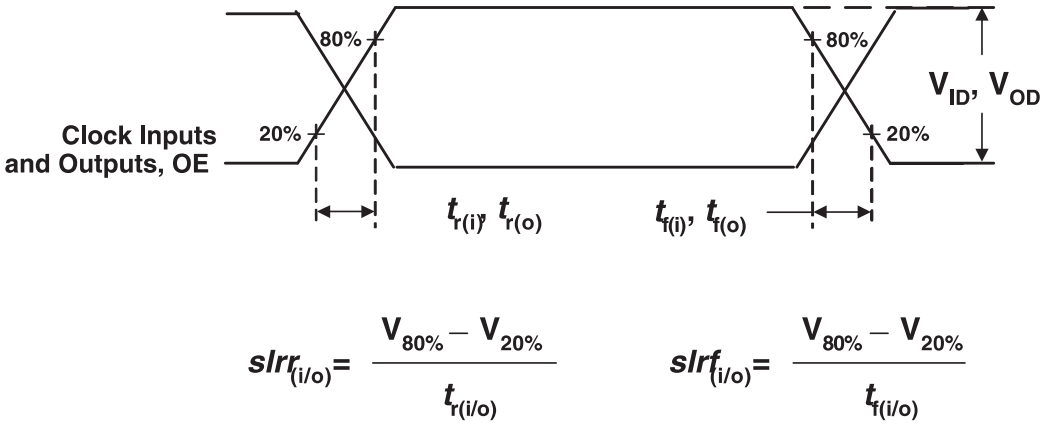


Figure 10. Input and Output Slew Rates

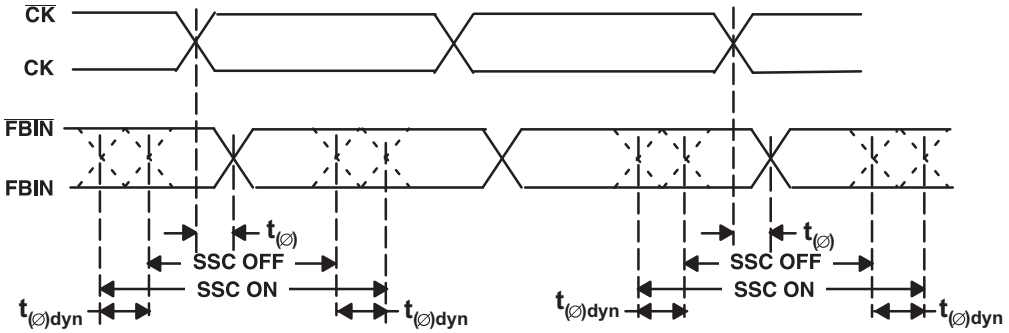


Figure 11. Dynamic Phase Offset

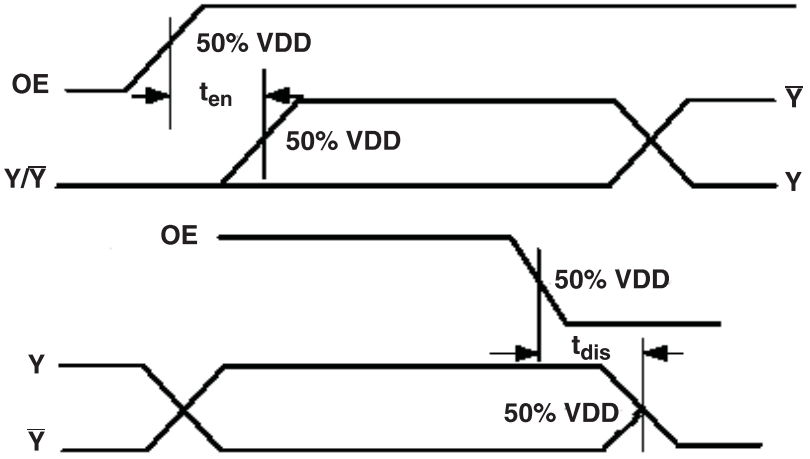
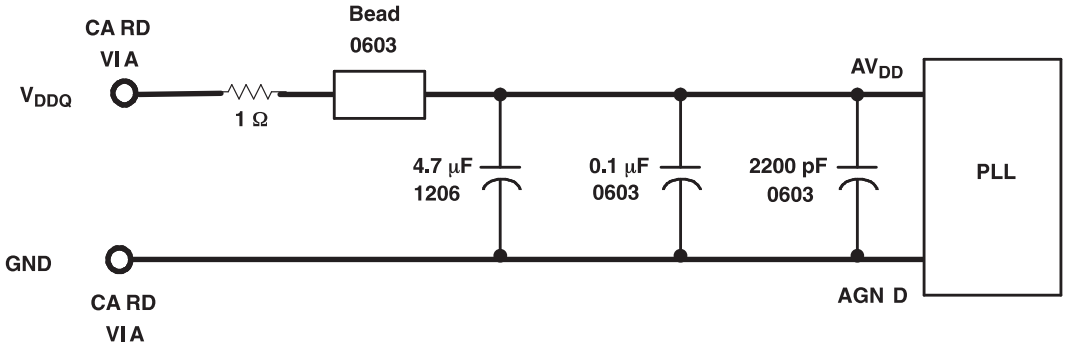


Figure 12. Time Delay Between OE and Clock Output (Y, $\overline{Y}$)



A. Place the 2200-pF capacitor close to the PLL.

B. Use a wide trace for the PLL analog power and ground. Connect PLL and capacitors to AGND trace and connect trace to one GND via (farthest from the PLL).

C. Recommended bead: Fair-Rite PN 2506036017Y0 or equilvalent (0.8Ω dc maximum, 600Ω at 100 MHz).

Figure 13. Recommended AV_{DD} Filtering

PACKAGING INFORMATION

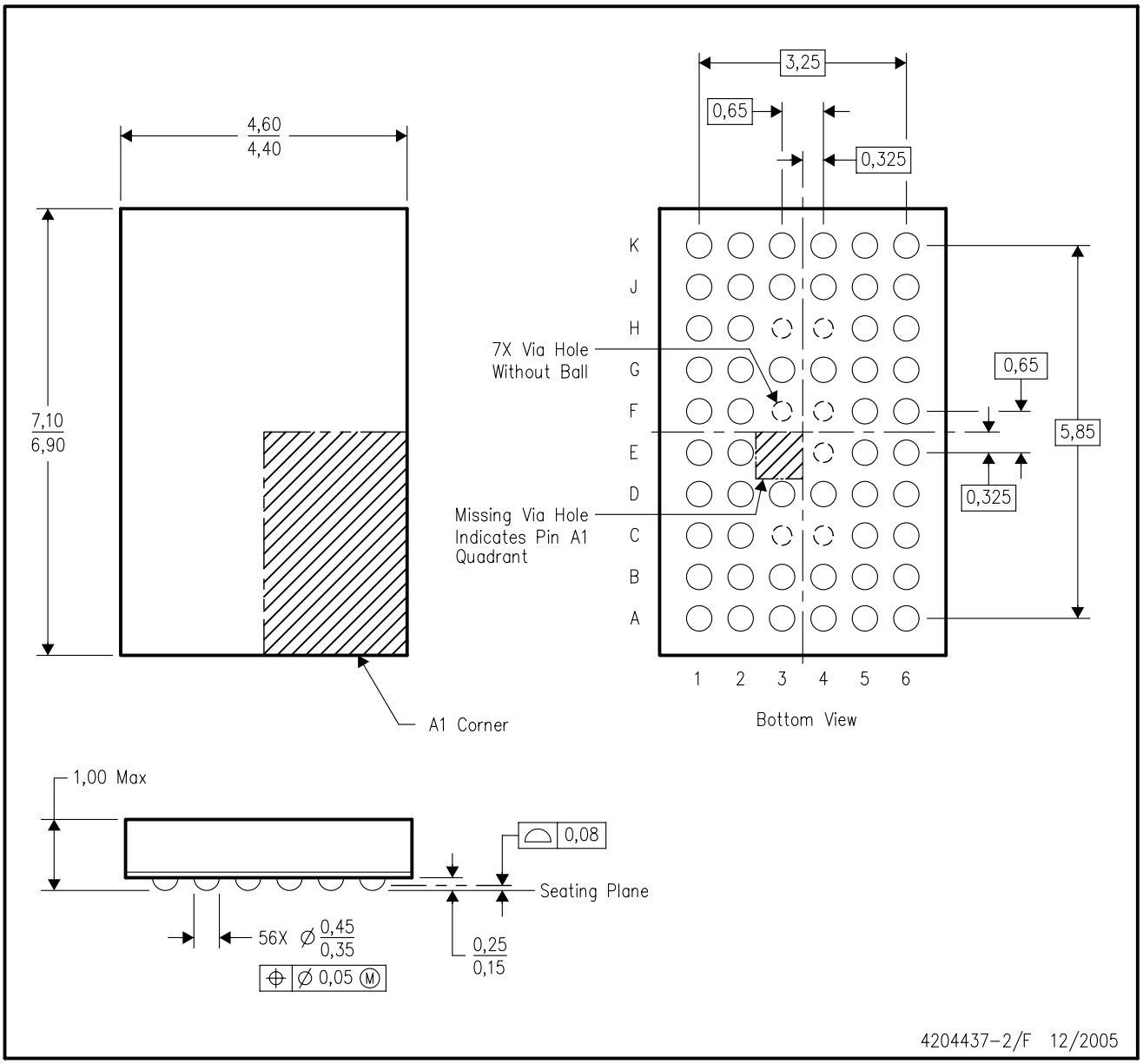
Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CDCU2A877ZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	52	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-2-260C-1 YEAR
CDCU2A877ZQLT	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	52	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-2-260C-1 YEAR

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

ZQL (R–PBGA–N52) PLASTIC BALL GRID ARRAY



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MO–225 variation BA.
D. This package is lead–free. Refer to the 52 GQL package (drawing 4200583) for tin–lead (SnPb).

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